BGA612

Silicon Germanium Broadband MMIC Amplifier

RF & Protection Devices



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BGA612, Silicon Germanium Broadband MMIC Amplifier

Revision History: 2011-09-02, Rev. 2.1

Previous Version: 2003-11-04

Page	Subjects (major changes since last revision)			
All	New Chip Version with integrated ESD protection			
5	Electrical Characteristics slightly changed			
7-8	Figures updated			
All	Document layout change			

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Data Sheet 3 Rev. 2.1, 2011-09-02



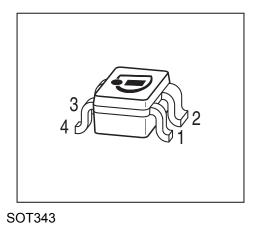
Silicon Germanium Broadband MMIC Amplifier

1 Silicon Germanium Broadband MMIC Amplifier

Feature

- Cascadable 50 Ω-gain block
- 3 dB-bandwidth: DC to 2.8 GHz with 17.5 dB typical gain at 1.0 GHz
- Compression point P_{-1dB} = 7 dBm at 2.0 GHz
- Noise figure $F_{50\Omega}$ = 2.1 dB at 2 GHz
- · Absolute stable
- 70 GHz f_T Silicon Germanium technology
- 1 kV HBM ESD protection (Pin-to-Pin)
- Pb-free (RoHS compliant) package





Applications

- Driver amplifier for GSM/PCS/CDMA/UMTS
- Broadband amplifier for SAT-TV & LNBs
- · Broadband amplifier for CATV

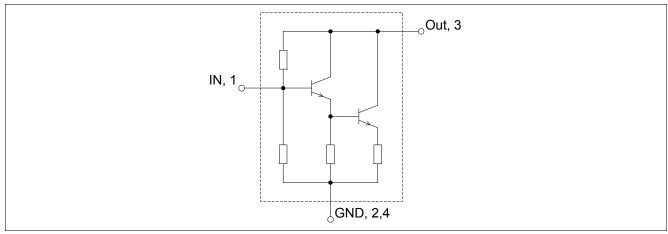


Figure 1 Pin connection

Description

BGA612 is a broadband matched, general purpose MMIC amplifier in a Darlington configuration. It is optimized for a typical supply current of 20 mA.

The BGA612 is based on Infineon Technologies' B7HF Silicon Germanium technology.

Туре	Package	Marking
BGA612	SOT343	BNs

Note: **ESD:** Electrostatic discharge sensitive device, observe handling precaution



Electrical Characteristics

Maximum Ratings

Table 1 Maximum ratings

Parameter	Symbol	Limit Value	Unit
Device voltage	V_{D}	2.8	V
Device current	I_{D}	80	mA
Current into pin In	I_{in}	0.7	mA
Input power ¹⁾	P_{in}	10	dBm
Total power dissipation, $T_{\rm S}$ < 105 °C ²⁾	P_{tot}	225	mW
Junction temperature	T_{J}	150	°C
Ambient temperature range	T_{A}	-65 150	°C
Storage temperature range	T_{STG}	-65 150	°C
ESD capability all pins (HBM: JESD22-A114)	V _{ESD}	1000	V

¹⁾ Valid for $Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω , $V_{\rm CC}$ = 5 V, $R_{\rm Bias}$ = 135 Ω

Note: All Voltages refer to GND-Node

Thermal resistance

Table 2 Thermal resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	200	K/W

¹⁾ For calculation of $R_{\mathrm{th,IA}}$ please refer to Application Note Thermal Resistance

2 Electrical Characteristics

Electrical characteristics at $T_{\rm A}$ = 25 °C (measured in test circuit specified in **Figure 2**) $V_{\rm CC}$ = 5 V, $R_{\rm Bias}$ = 135 Ω , Frequency = 2 GHz, unless otherwise specified

Table 3 Electrical Characteristics

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Insertion power gain	$ S_{21} ^2$		18.0		dB	f = 0.1 GHz
			17.5		dB	f = 1.0 GHz
			16.3		dB	f = 2.0 GHz
Noise figure ($Z_{\rm S}$ = 50 Ω)	$F_{50\Omega}$		1.8		dB	f = 0.1 GHz
			2.0		dB	f = 1.0 GHz
			2.1		dB	f = 2.0 GHz
Output power at 1 dB gain compression	$P_{ ext{-1dB}}$		7		dBm	
Output third order intercept point	OIP_3		17		dBm	
Input return loss	RL_{in}		17		dB	
Output return loss	RL_{out}		17		dB	
Total device current	I_{D}		20		mA	

²⁾ $\ensuremath{\mathit{T}_{\mathrm{S}}}$ is measured on the ground lead at the soldering point



Electrical Characteristics

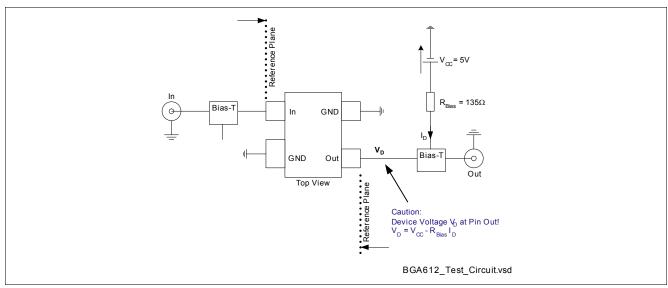
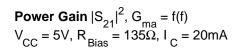


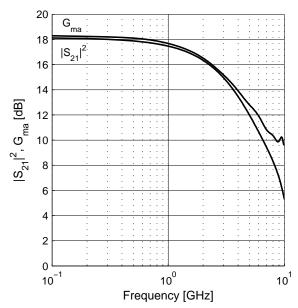
Figure 2 Test Circuit for Electrical Characteristics and S-Parameter



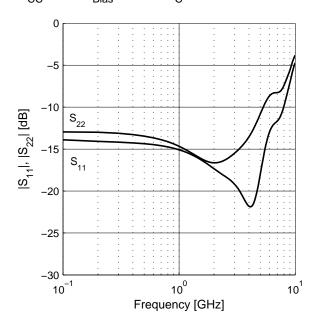
Measured Parameters

3 Measured Parameters

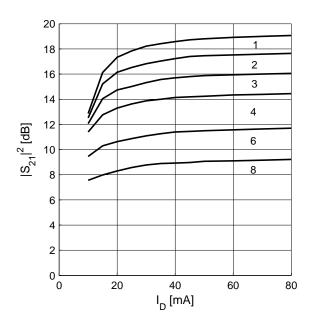




$$\begin{array}{l} \textbf{Matching} \; |\textbf{S}_{11}|, \; |\textbf{S}_{22}| = \textbf{f(f)} \\ \textbf{V}_{CC} = \textbf{5V}, \; \textbf{R}_{Bias} = \textbf{135}\Omega, \; \textbf{I}_{\;C} = \textbf{20mA} \\ \end{array}$$

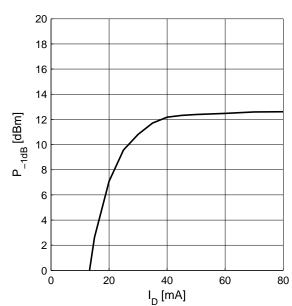


Power Gain $|S_{21}| = f(I_D)$ f = parameter in GHz



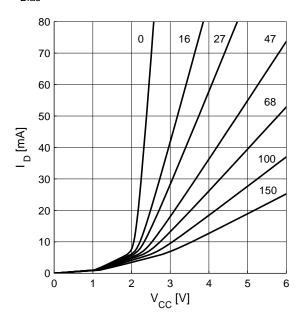
Output Compression Point

$$\mathsf{P}_{-\mathsf{1dB}} = \mathsf{f}(\mathsf{I}_{\mathsf{D}}),\,\mathsf{f} = \mathsf{2GHz}$$

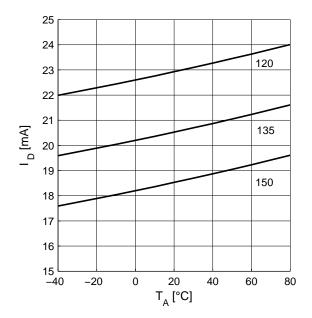




Measured Parameters

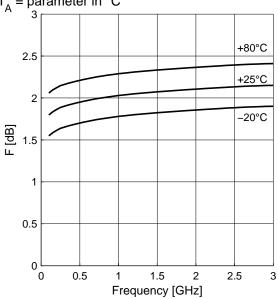


Device Current I
$$_{\rm D}$$
 = f(T $_{\rm A}$)
V $_{\rm CC}$ = 5V, R $_{\rm Bias}$ = parameter in Ω



Noise figure F = f(f)

$$V_{CC} = 5V$$
, $R_{Bias} = 135\Omega$, $Z_{S} = 50\Omega$
 $T_{A} = parameter in °C$





Package Information

4 Package Information

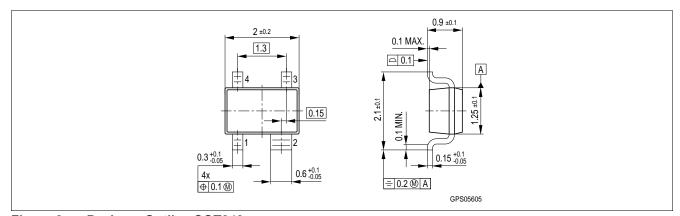


Figure 3 Package Outline SOT343

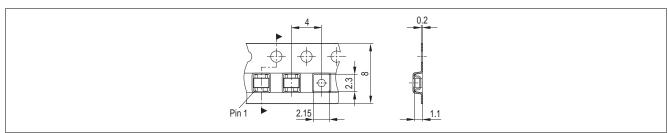


Figure 4 Tape for SOT343

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